

**PATENT ASSIGNMENT**

Electronic Version v1.1  
 Stylesheet Version v1.1

<b>SUBMISSION TYPE:</b>	NEW ASSIGNMENT
<b>NATURE OF CONVEYANCE:</b>	ASSIGNMENT
<b>CONVEYING PARTY DATA</b>	
<b>Name</b>	<b>Execution Date</b>
Wen-Kun Yang	11/23/2006
<b>RECEIVING PARTY DATA</b>	
<b>Name:</b>	Advanced Chip Engineering Technology Inc.
<b>Street Address:</b>	No. 65, Guangfu N. Rd.
<b>Internal Address:</b>	Hukou Township
<b>City:</b>	Hsinchu County
<b>State/Country:</b>	TAIWAN
<b>Postal Code:</b>	303
<b>PROPERTY NUMBERS Total: 1</b>	
<b>Property Type</b>	<b>Number</b>
Application Number:	11567795
<b>CORRESPONDENCE DATA</b>	
<b>Fax Number:</b>	(440)684-1095
<i>Correspondence will be sent via US Mail when the fax attempt is unsuccessful.</i>	
<b>Phone:</b>	440-684-1090
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<b>ATTORNEY DOCKET NUMBER:</b>	HK9389US
<b>NAME OF SUBMITTER:</b>	Michael A. Jaffe
<b>Total Attachments: 2</b> source=HK9389US-Assignment#page1.tif source=HK9389US-Assignment#page2.tif	

OP \$40.00 11567795

**PATENT**

**500190009**

**REEL: 018595 FRAME: 0189**

Practitioner's Docket No. HK9389US

**PATENT**

For: U.S. Rights  
For: U.S. Application  
By: Inventor

**ASSIGNMENT OF INVENTION**

In consideration of the payment by ASSIGNEE to ASSIGNOR of the sum of One Dollar (\$1.00), the receipt of which is hereby acknowledged, and for other good and valuable consideration,

**ASSIGNOR(S):**

Wen-Kim YANG  
(Given Name) (Middle Initial or Name) (Family or Last Name)  
Address No 47, Lane 6, An-Kang St., Hsin-Chu City, Taiwan, R.O.C.  
Citizenship Taiwan, R.O.C.

hereby sells, assigns and transfers to:

**ASSIGNEE:** Name Advanced Chip Engineering Technology Inc.  
Address No. 65, Guangfu N. Rd., Hukou Township, Hsinchu County 303,  
Taiwan, R.O.C.  
Corporation of Taiwan, R.O.C.

and the successors, assigns and legal representatives of the ASSIGNEE the entire right, title and interest for the United States and its territorial possessions in and to any and all improvements which are disclosed in the invention entitled:

Structure and Process for WL-CSP with Metal Cover

and which is found in (37 C.F.R. § 3.21) U.S. patent application executed on even date herewith or [XX] in Application No. \_\_\_\_\_, filed on \_\_\_\_\_ and, in and to, all Letters Patent to be obtained for said invention by the above application or any continuation, division, renewal, or substitute thereof, and as to letters patent any reissue or re-examination thereof.

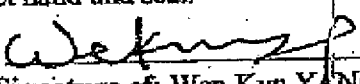
ASSIGNOR hereby covenants that no assignment, sale, agreement or encumbrance has been or will be made or entered into which would conflict with this assignment.

ASSIGNOR further covenants that ASSIGNEE will, upon its request, be provided promptly with all pertinent facts and documents relating to said invention and said Letters Patent and legal equivalents as may be known and accessible to ASSIGNOR and will testify as to the same in any interference, litigation or proceeding related thereto and will promptly execute and deliver to ASSIGNEE or its legal representatives any and all papers, instruments or affidavits required to apply for, obtain, maintain, issue and enforce said application, said invention and said Letters Patent and said equivalents thereof which may be necessary or desirable to carry out the purposes thereof.

(Assignment of Invention—page 1 of 2)

IN WITNESS WHEREOF, I have hereunto set hand and seal.

Date: NOV. 23, 2006



Signature of: Wen-Kun YANG  
(Given Name, Middle Initial or Name, Family or Last Name)

(Assignment of Invention—page 2 of 2)